



Final Product Change Notification

201203009F03

Issue Date: 22-Jun-2014

Effective Date: 20-Sep-2014

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QUALITY

Management Summary

Announcement of products processed in PM72 to be transferred within NXP Nijmegen from ICN6 to ICN8 due to factory closure

Change Category

<input checked="" type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input checked="" type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Transfer PM72 process from ICN6 to ICN8 within NXP Nijmegen (The Netherlands)

Details of this Change

Transfer within NXP Nijmegen (The Netherlands) from ICN6 (PM72 process) to ICN8 (PC110DMB/TM process)

- Process and products will be transferred in 2013, production ramp down and closure of ICN6 planned 1 January 2014
- Product Line System Management will introduce the following enhancements;
 - PCA9515A base die will move to the Higher ESD performing version.
 - PCA9517A will be diffused on the C100 process.
 - PCA9517 family of parts will use the PCA9517A die.
- No change in ordering code 12NC's and product type number

Why do we Implement this Change

- Move production to 8" wafers
- Capacity increase to address customer demand,
- Using the 'improved' PCA9515A base die and the PCA9517A die provides the customer with better ESD performance.

- Consolidating the PCA9517 and PCA9517A provides for logistics control, enhancing Operational efficiency in NXP.
- changes are operationally transparent to the customers application.

Identification of Affected Products

Applied wafer fab is indicated on the third line of the product marking (top side) first character, if space permits:

"U"= NXP ICN6

"T"= NXP ICN8

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment 30-Sep-2014

Impact

- No impact on part functionality
- No change in data sheet, form, fit, function, quality or reliability anticipated

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 22-Jul-2014.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please [contact NXP "Global Quality Support Team"](#).

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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